

# Bill of Materials

**TI DESIGNS**

TIDA-00731 - IEC ESD/EFT/Surge Protected RS-485

Item	Qty	Reference	Value	Manufacturer	Manufacturer Part Number	PCB Footprint
1	1	C1	10 $\mu$ F	Any (5V+ Rating)	T491D106K025AT	7343-31 (EIA)
2	1	C2	2.2 $\mu$ F	Any (5V+ Rating)	GRM31CR71H225KA88L	1206'
3	1	C3	1.0 $\mu$ F	Any (5V+ Rating)	C0805C105J4RACTU	0805'
4	2	C4, C5	0.1 $\mu$ F	Any (5V+ Rating)	GRM188R71H104KA93D	0603'
5	2	C6, C7	DNI	Any (5V+ Rating)	DNI	DNI
6	1	D1	CDSOT23-SM712	Bourns Inc	CDSOT23-SM712	SOT-23-3
7	2	J1, J2	Banana Plug - Metal	Emerson Network Power	108-0740-001	4mm
8	12	JMP1, JMP2, JMP3, JMP4	HTSW-150-07-G-S	Samtec Inc	HTSW-150-07-G-S	0.1"
9	2	JMP5, JMP6	HTSW-150-07-G-S	Samtec Inc	HTSW-150-07-G-S	0.1"
10	2	MOV1, MOV2	MOV-14D561KTR	Bourns Inc	MOV-10D201K	Disc 10mm
11	2	P1, P2	Banana Plug - Metal	Emerson Network Power	108-0740-001	4mm
12	7	R1, R2, R3, R4, R5, R6, R7	49.9'	Any (1% Tolerance)	ERJ-3EKF49R9V	0603'
13	2	R8, R9	10.0 ohm	Any (1% Tolerance)	CRCW060310R0FKEAHP	0603'
14	2	TBU1, TBU2	TBU-CA065-200-WH	Bourns	TBU-CA065-200-WH	SMD 6.50mm x 4.00mm
15	1	U1	SN65HVD82	Texas Instruments	SN65HVD82	SOIC

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